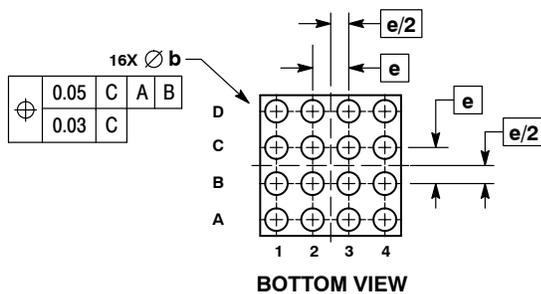
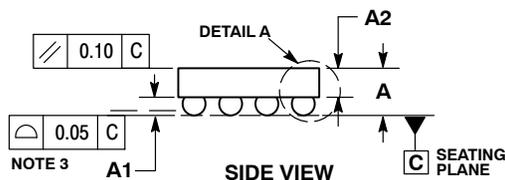
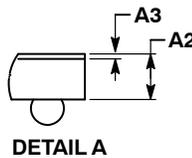
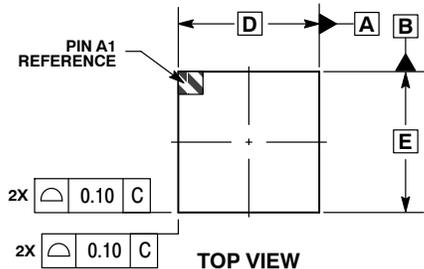




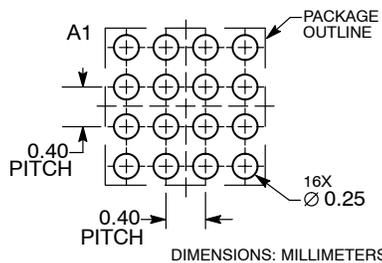
SCALE 4:1

WLCSP16, 1.56x1.56  
CASE 567GF  
ISSUE D

DATE 24 APR 2014



RECOMMENDED  
SOLDERING FOOTPRINT\*



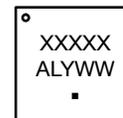
\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.60
A1	0.17	0.23
A2	0.33	0.39
A3	0.04 BSC	
b	0.24	0.29
D	1.56 BSC	
E	1.56 BSC	
e	0.40 BSC	

GENERIC  
MARKING DIAGRAM\*



- XXXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- WW = Work Week
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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